

**Amendments to the Specification:**

Please amend the abstract as follows:

Method for conditioning of an electronic microcircuit ~~(1)~~ designed for the production of an electronic module which can be glued by means of a simple glue or by soldering. For this purpose the microchip has a geometric shape compatible with a recess in a card ~~(19)~~ provided to accommodate it and has a means serving as a mask ~~(7)~~ compatible with the card. Ultimately this mask also serves to prevent an outflow of a resin coating ~~(14)~~ used to protect a chip ~~(10)~~ included in this type of module. The mask is glued to a support ~~(2)~~ having, on a first face ~~(3)~~, the contact area ~~(4)~~, and on a second face ~~(6)~~ the mask and the chip. The mask includes a window ~~(9)~~ determining the placement of the chip.

~~Figure 1~~